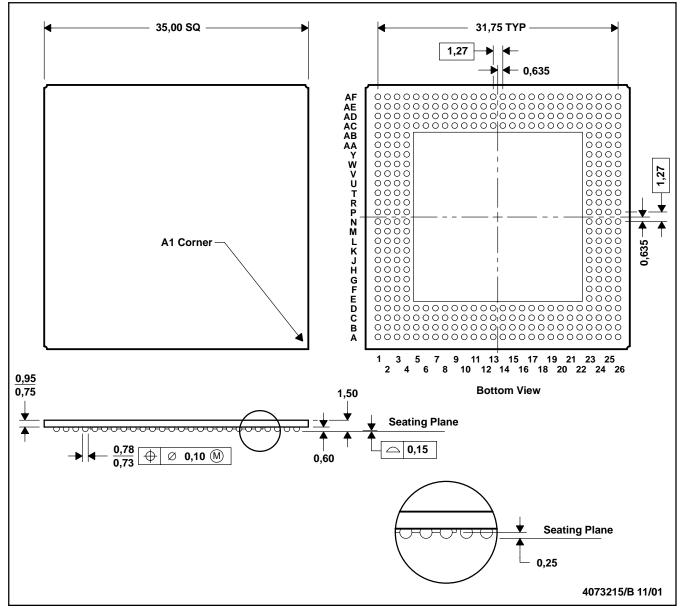
MECHANICAL DATA

MPBG015A-FEBRUARY 1996 - REVISED JANUARY 2002

PLASTIC BALL GRID ARRAY

GGH (S-PBGA-N352)



NOTES: A. All linear dimensions are in millimeters. B. This drawing is subject to change without notice.



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